

- selected from among the group of N-methyl-2-pyrrolidone (NMP), N,N-dimethyl formamide (DMF), and N,N-dimethylacetoamide (DMAc). Said lower boiling point solvents applicable in the present invention are such as tetrahydrofuran (THF), methanol, ethanol, 1-propanol and the like".
- (2) The expression "and one or more kind(s) of solvent having a higher boiling point of 100°C or more" which appears on Claim 1 of page 22 should be amended as "one or more kind(s) of solvent(s) having a high boiling point selected from among the group of N-methyl-2-pyrrolidone (NMP), N,N-dimethyl formamide (DMF), and N,N-dimethylacetoamide (DMAc)".
 - (3) The expression "a polyimide precursor solution" which appears on Claim 1 of page 22 should be amended as "a polyimide precursor solution for coating".
 - (4) The expression "one or more kind(s) of solvent selected from among the group of N-methyl-2-pyrrolidone (NMP), N, N-dimethyl formamide (DMF), and N, N-dimethylacetoamide (DMAc)" which appears on Claim 2 of page 22 and 23 should be amended as "one or more kind(s)"
 - (5) The expression "a polyimide precursor solution" which appears on Claim 2 of page 22 should be amended as "a polyimide precursor solution for coating"
 - (6) The expression "a polyimide precursor solution" which appears on Claim 3 of page 23 should be amended as "a polyimide precursor solution for coating"
 - (7) The expression "a polyimide precursor solution" which appears on Claim 4 of page 23 should be amended as "a polyimide precursor solution for coating"
 - (8) The expression "a polyimide precursor solution" which appears on Claim 5 of page 23 should be amended as "a polyimide precursor solution for coating"
 - (9) The expression "a polyimide precursor solution" which appears on Claim 6 of page 23 should be amended as "a polyimide precursor solution for coating"

- 2 -
(10) The expression "said polyimide precursor solution(s)" which appears on Claim 7 of page 23 should be amended as "said polyimide precursor solution(s) for coating"

5. List of Attached Documents

- (1) Replacement sheet of page 7 and 7 1/2 of Specification**
- (2) Replacement sheet of page 22 of Claims**
- (3) Replacement sheet of page 23 of Claims**

(Solvent mixture)

The solvent used in said polyimide precursor solution of the present invention is a mixture of one or more kind(s) of solvent having a lower boiling point (said boiling point(s) being at one atmospheric pressure) of under 100°C and one or more kind(s) of solvent having a high boiling point, said solvent being selected from among the group of N-methyl-2-pyrrolidone (NMP), N,N-dimethyl formamide (DMF), and N,N-dimethylacetoamide (DMAc). Said lower boiling point solvents applicable in the present invention are such as tetrahydrofuran (THF), methanol, ethanol, 1-propanol and the like.

Said solvent(s) having the lower boiling point(s) used in the present invention are such as tetrahydrofuran (THF), methanol, ethanol, 1-propanol and the like. Said solvent(s) having the higher boiling point(s) used in the present invention are such as N-methyl-2-pyrrolidone (NMP), N, N'-dimethylformamide (DMF), N, N'-dimethyl aceto amide (DMAc) and the like.

The said solvent(s) used in said polyimide precursor solution of the present invention are a mixture of one or more kind(s) of solvent L having lower boiling point(s), (hereafter L), and one or more kind(s) of solvent H having higher boiling point(s)(hereafter H), and said solvent H is contained in said solvent mixture in the range of between 5 and 55% by weight, more desirably 5 and 40% by weight, and most desirably 10 and 35% by weight.

In a case where said solvent H is contained in said solvent mixture less than 5% by weight, said solvent mixture in said polyimide precursor solution is apt to evaporate, resulting in fears that said coating film will be uneven.

Further, in a case where said solvent H is contained in said solvent mixture more than 40% by weight, said solvent mixture in said polyimide precursor solution evaporates slowly, so that said surface coated solution may droop during the exceedingly slow drying process, resulting in fears that the dried coating film be uneven.

The concentration of said polyimide precursor in said polyimide precursor solution of the present invention may preferably be in the range of between 0.1 and 60% by weight, more preferably between 1 and 25% by weight, and most preferably between 5 and 20% by weight.

Further, in a case where the solvent to solid ratio of H in said polyimide

precursor is set to be at a weight ratio of 1.5 or less, drooping of said solution can be effectively prevented during the coating process.

Accordingly, in this case, even ratio of said solvent H is raised to be 55% by weight, the drooping of said solution does not occur.